

FR601 THRU FR607

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FR601 THRU FR607

6.0A Axial Leaded Fast Recovery Rectifiers - 50V-1000V

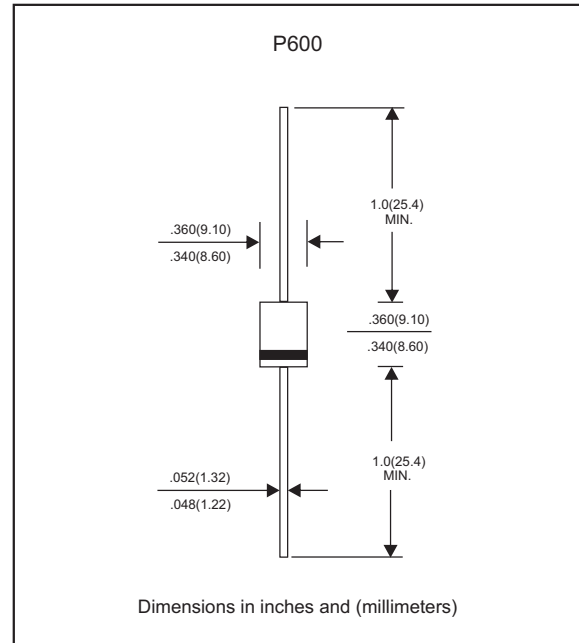
Features

- Axial lead type devices for through hole design.
- High current capability.
- Fast switching for high efficiency.
- High surge capability.
- Silicon rubber coating chip junction.
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen-free parts, ex. FR601-H.

Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, P600
- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: Color band denotes cathode end
- Mounting Position : Any
- Weight : Approximated 1.75 gram

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^{\circ}C$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I_o			6.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			300	A
Reverse current	$V_R = V_{RRM} T_J = 25^{\circ}C$	I_R			5.0	μA
	$V_R = V_{RRM} T_J = 100^{\circ}C$				150	
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		100		pF
Storage temperature		T_{STG}	-65		+175	$^{\circ}C$

SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	t_{rr}^{*5} (ns)	Operating temperature $T_J, (^{\circ}C)$
FR601	50	35	50	1.30	150	-55 to +125
FR602	100	70	100			
FR603	200	140	200			
FR604	400	280	400		250	
FR605	600	420	600			
FR606	800	560	800		500	
FR607	1000	700	1000			

- *1 Repetitive peak reverse voltage
- *2 RMS voltage
- *3 Continuous reverse voltage
- *4 Maximum forward voltage@ $I_F=6.0A$
- *5 Maximum Reverse recovery time, note 1

Note 1. Reverse recovery time test condition, $I_F=0.5A, I_R=1.0A, I_{RR}=0.25A$

Rating and characteristic curves (FR601 THRU FR607)

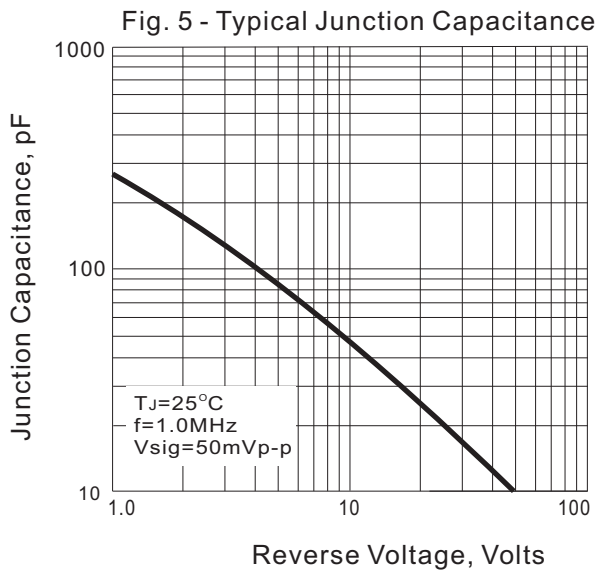
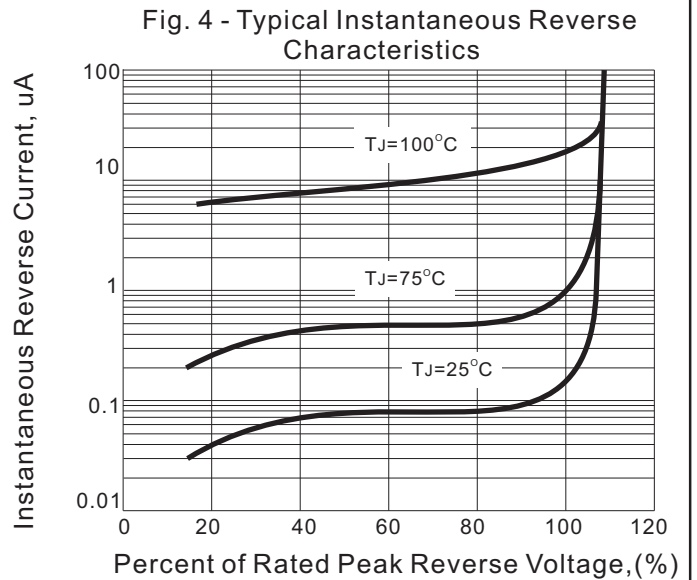
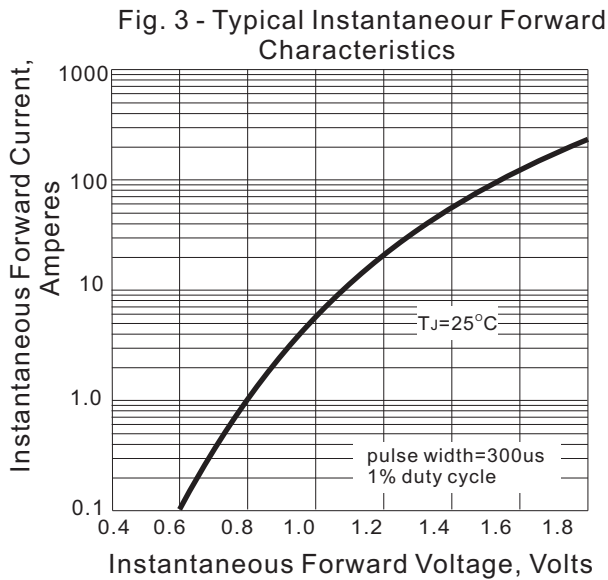
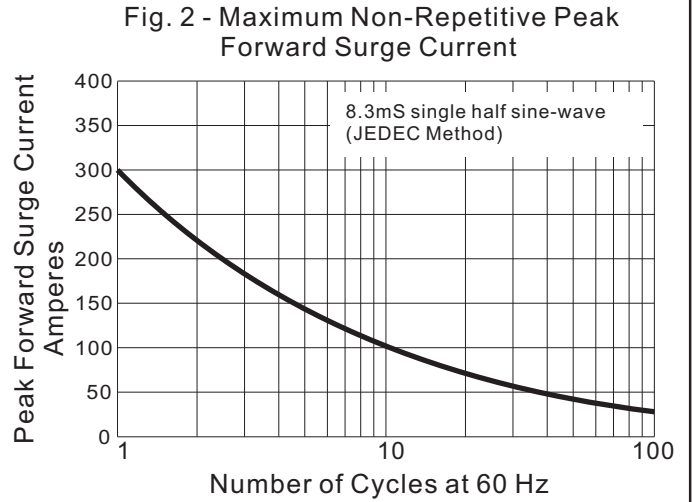
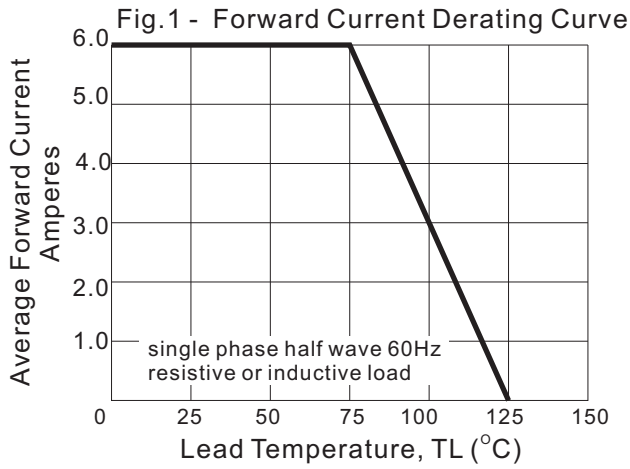
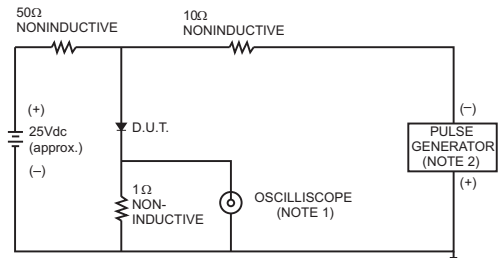
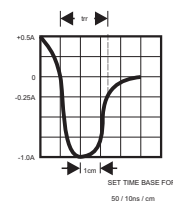


Fig. 6 - Test Circuit Diagram and Reverse Recovery Time Characteristic





- NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm.22pF.
2. Rise Time= 10ns max., Source Impedance= 50 ohms.



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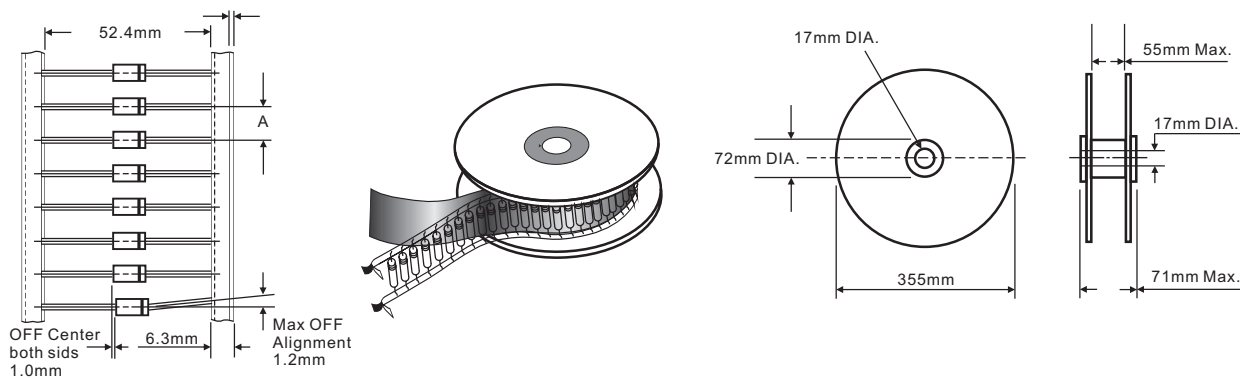
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
FR601	FR601
FR602	FR602
FR603	FR603
FR604	FR604
FR605	FR605
FR606	FR606
FR607	FR607

Taping & bulk specifications for AXIAL devices



REEL PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / REEL)	COMPONENT SPACING "A" in FIG. A	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
P600	1,000	5 mm	360 * 340 * 370	4,000	9.5

AMMO PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
P600	500	260 * 83 * 160	440 * 270 * 340	5,000	12.0

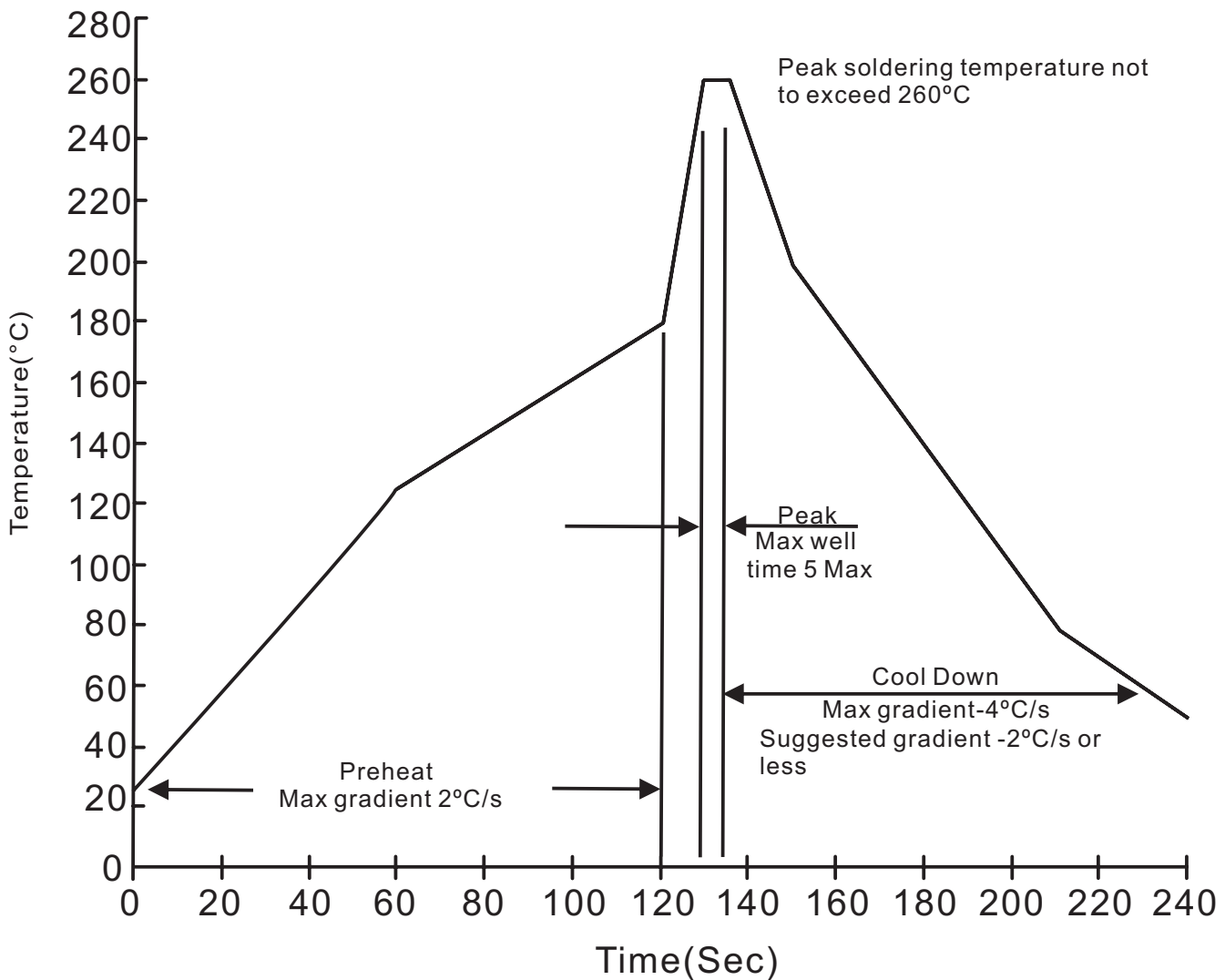
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BULK PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
P600	250	305 * 73 * 40	347 * 320 * 271	6,000	14.5

Suggested thermal profiles for soldering processes

1. Lead free temperature profile wave-soldering



FR601 THRU FR607**High reliability test capabilities**

Item Test	Conditions	Reference
1. Solder Resistance	at 260±5°C for 10±2sec. immerse body into solder 1/16"±1/32"	MIL-STD-750D METHOD-2031
2. Solderability	at 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
3. Pull Test	2.0kg in axial lead direction for 10 sec. $I_F = I_O$	MIL-STD-202F METHOD-211A
4. Bend Lead	2.0kg weight applied to each lead bending arc 90°±5° for 3 times	MIL-STD-202F METHOD-211A
5. High Temperature Reverse Bias	$V_R = 80\%$ rate at $T_J = 125^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
6. Forward Operation Life	Rated average rectifier current at $T_A = 25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
7. Intermittent Operation Life	$T_A = 25^\circ\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min, on and off for 500 cycles.	MIL-STD-750D METHOD-1036
8. Pressure Cooker	15P _{sig} at $T_A = 121^\circ\text{C}$ for 4 hrs.	JESD22-A102
9. Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
10. Forward Surge	8.3ms single half sine-wave one surge.	MIL-STD-750D METHOD-4066-2
11. Humidity	at $T_A = 85^\circ\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
12. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031